

EECS 151/251A

Spring 2023

Digital Design and Integrated Circuits

Instructor:
John Wawrzynek

Lecture 17: Memory Circuits and Blocks

## **Announcements**

Project spec & HW7 posted this week

#### Exam 1 Results 19 17 12 11 6 10 20 50 70 90 100 Minimum Maximum Std Dev 🚱 Median Mean

94.0

68.47

- Grades and Solutions posted today
- □ Regrades open for a week.

68.0

**35.0** 

**15.46** 



## **Outline**

- □ Memory Circuits
  - □ SRAM
  - □ DRAM
- □ Memory Blocks
  - □ Multi-ported RAM
  - Combining Memory blocks
  - □ FIFOs
  - □ FPGA memory blocks
  - □ Caches
  - □ Memory Blocks in the Project

# First, Some Memory Classifications:

- Hardwired (Read-only-memory-ROM)
- Programmable
  - Volatile
    - SRAM uses positive feedback (and restoration) to hold state
    - DRAM uses capacitive charge (only) to hold state
  - Non-volatile
    - Persistent state without power supplied
    - Ex: Flash Memory



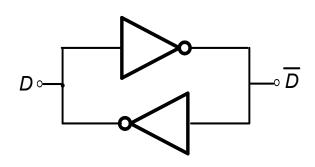
## **Memory Circuits**

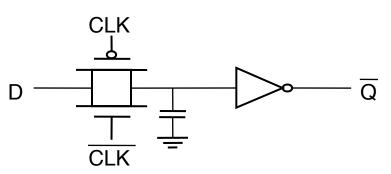
# Volatile Storage Mechanisms

These circuits represent the principles of storing a bit:

Static - feedback

**Dynamic** - charge

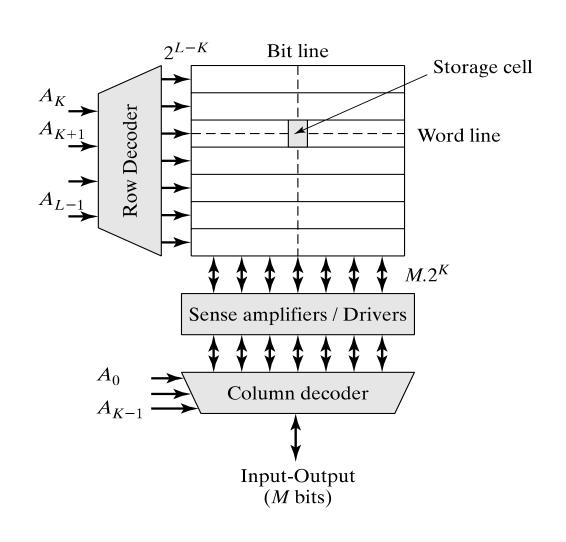




Circuit details differ, depending on application.

# Generic Memory Block Architecture

- Word lines used to select a row for reading or writing
- □ Bit lines carry data to/from periphery
- □ Core aspect ratio keep close to 1 to help balance delay on word line versus bit line
- Address bits are divided between the two decoders
- Row decoder used to select word line
- Column decoder used to select one or more columns for input/output of data

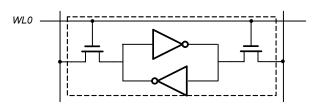


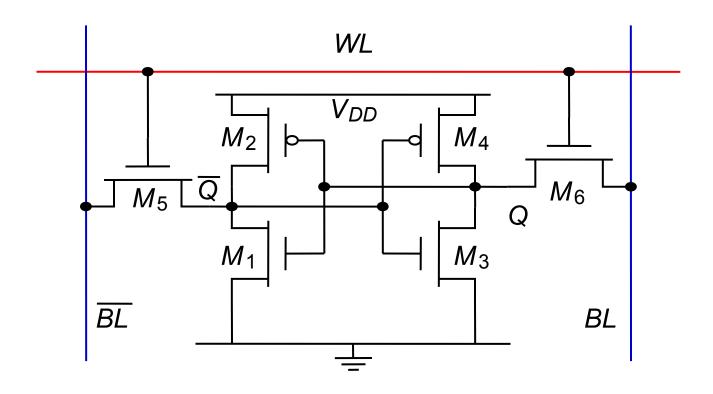


## **Memory - SRAM**

- Gets used for onchip memories.
   Caches, large register files, input/ output buffers, ...
- Compatible with logic processes.

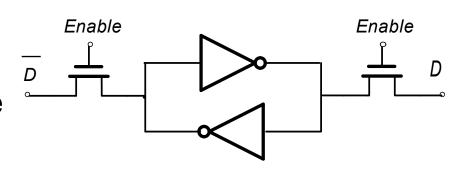
## 6-Transistor CMOS SRAM Cell



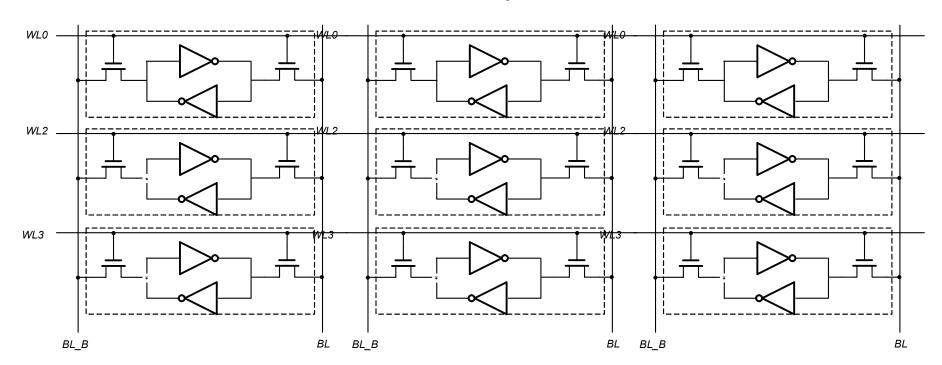


# Memory Cells

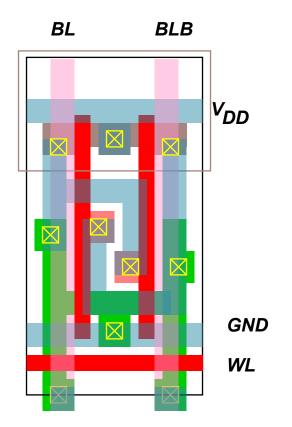
Complementary data values are written (read) from two sides

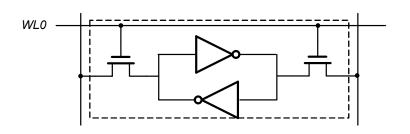


Cells stacked in 2D to form memory core.



# 6T-SRAM — Older Layout Style





V<sub>DD</sub> and GND: in M1(blue)

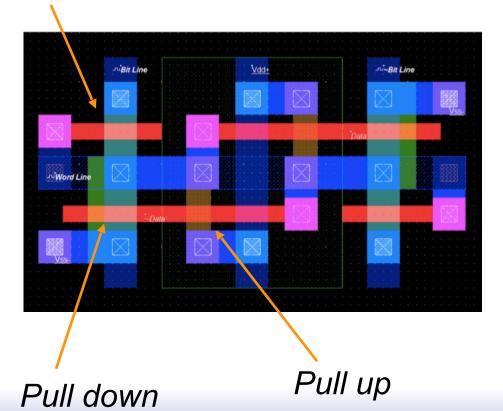
Bitlines: M2 (purple)

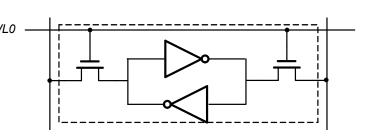
Wordline: poly-silicon (red)

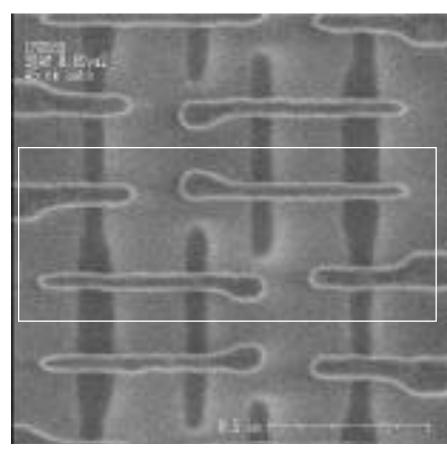
## Modern SRAM

## □ ST/Philips/Motorola

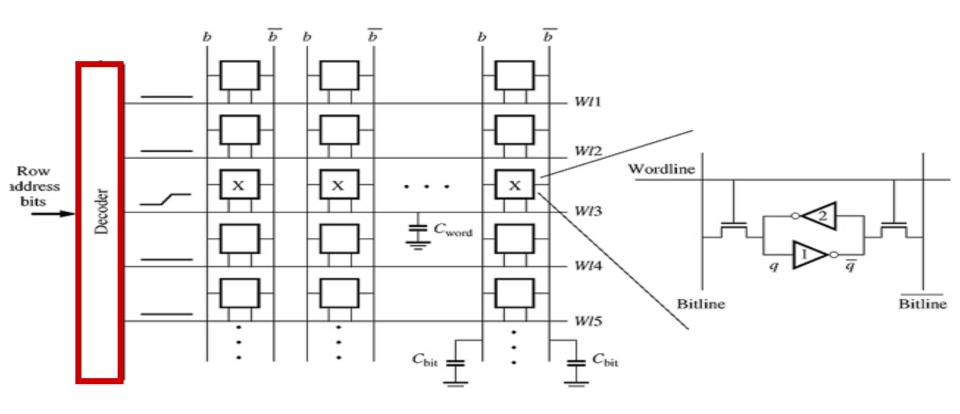
Access Transistor





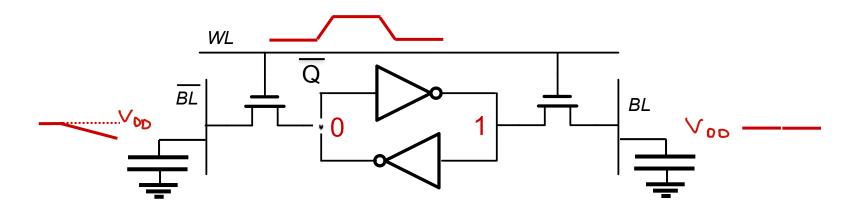


# SRAM read/write operations



# SRAM Operation - Read

- 1. Bit lines are "pre-charged" to VDD
- 2. Word line is driven high (pre-charger is turned off)
- 3. Cell pulls-down one bit line
- 4. Differential sensing circuit on periphery is activated to capture value on bit lines.

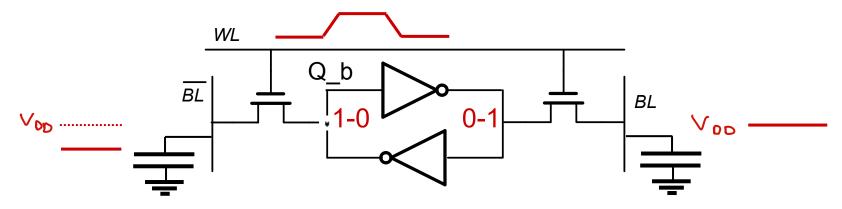


During read Q will get slightly pulled up when WL first goes high, but ...

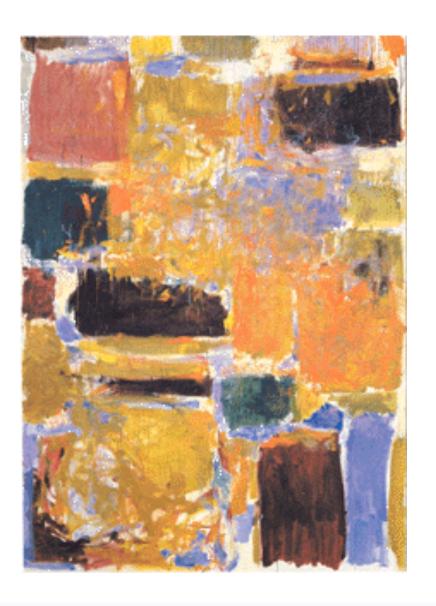
• But by sizing the transistors correctly, reading the cell will not destroy the stored value

# SRAM Operation - Write

- 1. Column driver circuit on periphery differentially drives the bit lines
- 2. Word line is driven high (column driver stays on)
- 3. One side of cell is driven low, flips the other side

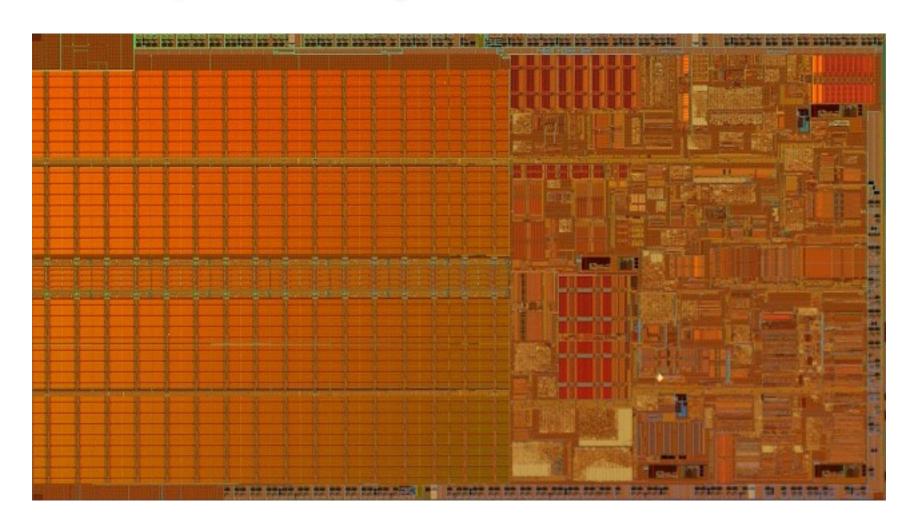


For successful write the access transistor needs to overpower the cell pullup. The transistors are sized to allow this to happen.



**Memory Periphery** 

# On-chip Memory



ARM A5 Photo

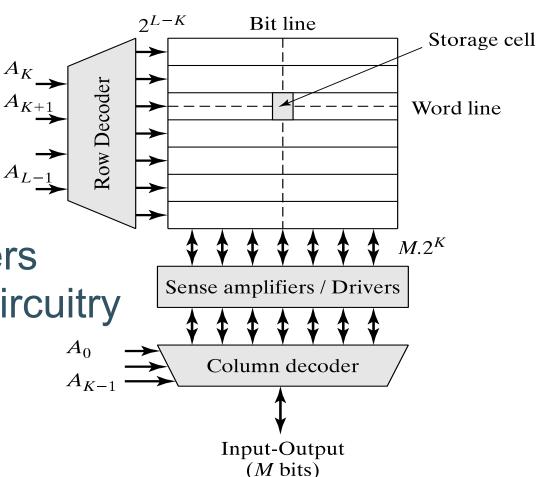
# Periphery

■ Decoders

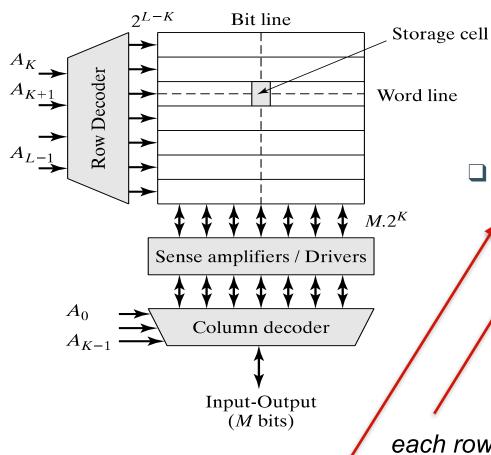
■ Sense Amplifiers

☐ Input/Output Buffers

☐ Control / Timing Circuitry



## Row Decoder



- L total address bits
- K for column decoding
- L-K for row decoding
- Row decoder expands L-K address lines into 2<sup>L-K</sup> word lines
- M bits per word
- Example: decoder for 8Kx8 memory block
  - core arranged as256x256 cells
  - Need 256 AND gates, each driving one word line

each row has 32 8-bit words (8x32=256)

8K x 8 means 8K words of 8-bits each

In this case: L=13 total address bits ( $2^{L}=8K$ ), K=5 ( $2^{K}=32$ ), L-K=8 ( $2^{L-K}=256$ )

## Row Decoders

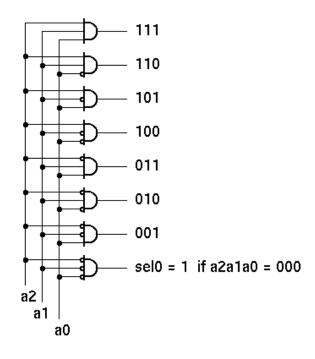
### (N)AND Decoder

$$WL_0 = A_0 A_1 A_2 A_3 A_4 A_5 A_6 A_7 A_8 A_9$$

$$WL_{511} = \bar{A}_0 A_1 A_2 A_3 A_4 A_5 A_6 A_7 A_8 A_9$$

### **NOR Decoder**

$$\begin{split} WL_0 &= \overline{A_0 + A_1 + A_2 + A_3 + A_4 + A_5 + A_6 + A_7 + A_8 + A_9} \\ WL_{511} &= \overline{A_0 + \overline{A}_1 + \overline{A}_2 + \overline{A}_3 + \overline{A}_4 + \overline{A}_5 + \overline{A}_6 + \overline{A}_7 + \overline{A}_8 + \overline{A}_9} \end{split}$$



Collection of 2<sup>L-K</sup> logic gates, but need to be dense and fast.

Naive solution would require L-K input gates: *Too big to pitch match to storage cells and too slow.* 

## **Predecoders**

•

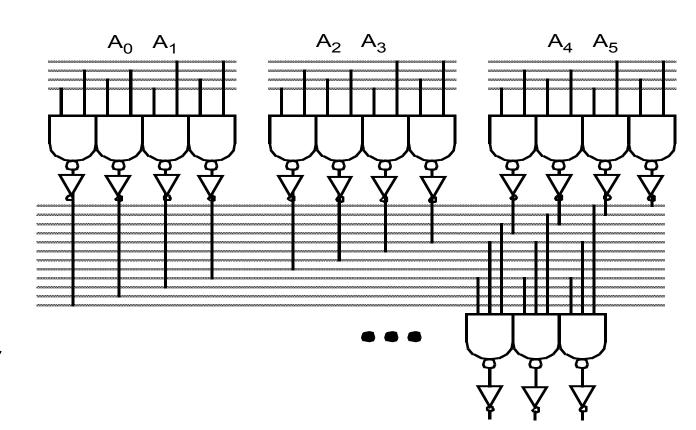
•

$$a_5 a_4 a_3 a_2 \overline{a_1} \overline{a_0}$$
 $a_5 a_4 a_3 a_2 \overline{a_1} a_0$ 
 $a_5 a_4 a_3 a_2 a_1 \overline{a_0}$ 
 $a_5 a_4 a_3 a_2 a_1 \overline{a_0}$ 
 $a_5 a_4 a_3 a_2 a_1 a_0$ 

- Use a single gate for each of the shared terms
  - E.g., from  $a_1, \overline{a_1}, a_0, \overline{a_0}$  generate four signals:
  - $\blacksquare$   $\overline{a_1} \, \overline{a_0}, \overline{a_1} \, a_0, a_1 \, \overline{a_0}, a_1 \, a_0$
- $\square$  Do same for  $a_5, a_4, a_3, a_2$
- □ In other words, we decode smaller groups of address bits first
  - And using the "predecoded" outputs to do the rest of the decoding

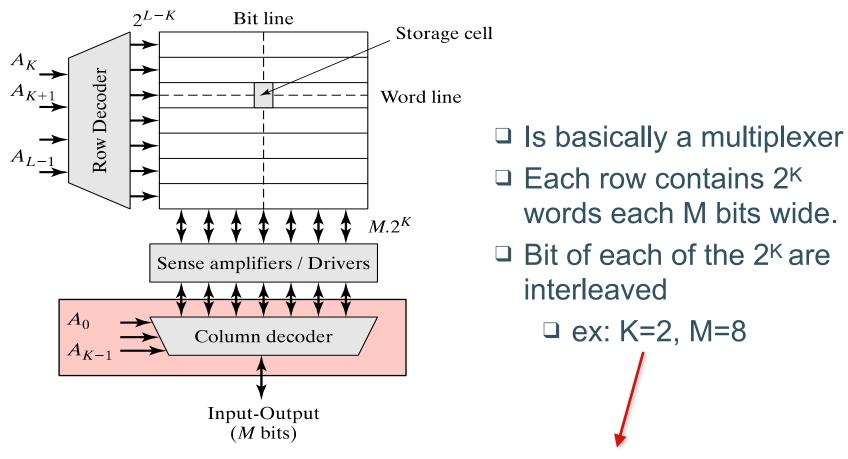
## Predecoder and Decoder

**Predecoders** 



Final Decoder

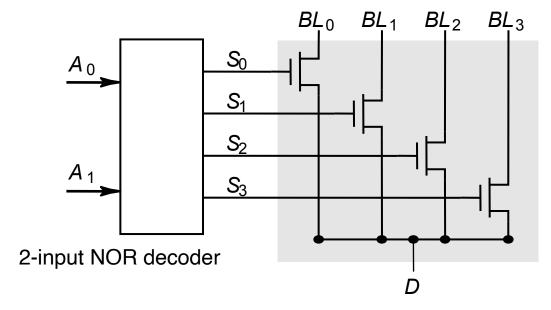
## Column "Decoder"



 $d_7c_7b_7a_7d_6c_6b_6a_6d_5c_5b_5a_5d_4c_4b_4a_4d_3c_3b_3a_3d_2c_2b_2a_2d_1c_1b_1a_1d_0c_0b_0a_0$ 

4 interleaved words A, B, C, D

### 4-input pass-transistor based Column Decoder (for read)



(actual circuit would use a "differential signaling")

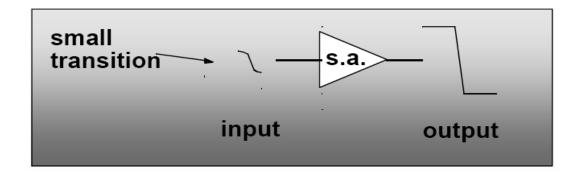
### decoder shared across all 2<sup>K x</sup> M row bits

Advantages: speed (Only one extra transistor in signal path, share sense amp)

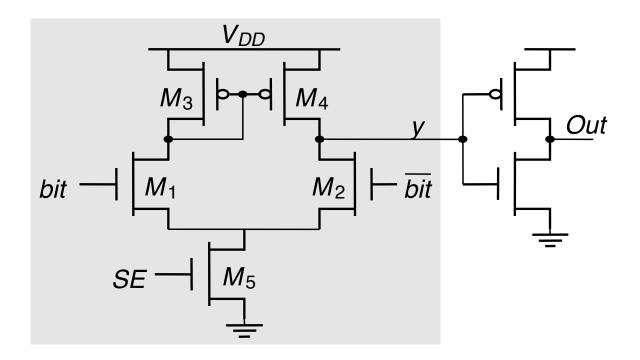
## Sense Amplifiers Speed Reading

large Capacitance of bit lines  $\tau_p \propto \frac{C \cdot \Delta V}{I_{av}} \leftarrow \frac{make \ as \ small \ as \ possible}{small}$ 

Idea: Use "Sense Amplifier"

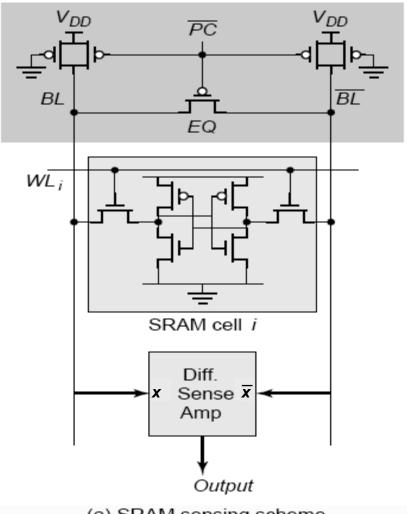


# Differential Sense Amplifier



Classic Differential Amp structure - basis of opAmp

# Differential Sensing — SRAM



(a) SRAM sensing scheme